

# **SPECIFICATION**

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SPEC. NO.:	PS-5068	37-XXXXX-XXX	REVISION: O			
PRODUCT N	JAME:	1.0mm NON ZIF FPC	CONN			
PRODUCT N	Ю:	50686 series: 50687 ser	ies.			

PREPARED:	CHECKED:	APPROVED:
Andrew	Carltso	Jason
DATE: <b>2010/019/10</b>	DATE: <b>2010/09/10</b>	DATE: <b>2010/09/14</b>

AC COM	nectors		Aces P/N: 5	0687 series	
TITLE:	1.0MM NON ZIF FF	C CONN.			
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6	INFRARED REFL	OW CONDIT	ION		7
7				EQUENCE	
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	AM NON ZIF F	PC CONN.	Aces P/N: 50687 series		
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Rev.	n History ECN#		Revision Description	Prepared	Date
0	1009031	Released		Andrew	2010/09/10



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### 2 SCOPE

This specification covers performance, tests and quality requirements for 1.0 mm pitch NON ZIF FPC connector.

### 3 APPLICABLE DOCUMENTS

EIA-364 ELECTRONICS INDUSTRIES ASSOCIATION

### 4 REQUIREMENTS

- 4.1 Design and Construction
  - 4.1.1 Product shall be of design, construction and physical dimensions specified on applicable product drawing.
  - 4.1.2 All materials conform to R.o.H.S. and the standard depends on TQ-WI-140101.
- 4.2 Materials and Finish
  - 4.2.1 Contact: High performance copper alloy (Phosphor Bronze)

Finish: (a) Contact Area: Refer to the drawing.

(b) Under plate: Refer to the drawing.

(c) Solder area: Refer to the drawing.

4.2.2 Housing: Thermoplastic or Thermoplastic High Temp., UL94V-0

#### 4.3 Ratings

4.3.1 Voltage: 50 Volts AC (per pin)/DC

4.3.2 Current: 0.5 Amperes (per pin)/DC

4.3.3 Operating Temperature : -40°C to +85°C

## 5 Performance

5.1. Test Requirements and Procedures Summary

Item	Requirement	Standard
Examination of Product	1 ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' ' '	Visual, dimensional and functional per applicable quality inspection plan.



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	ELECTRICAL	
Item	Requirement	Standard
Low Level Contact Resistance	55 m $\Omega$ Max.(initial)per contact $\triangle$ R 20 m $\Omega$ Max.	Mate connectors, measure by dry circuit, 20mV Max., 100mA Max. (EIA-364-23)
Insulation Resistance	100 M Ω Min.	Unmated connectors, apply 500 V DC between adjacent terminals. (EIA-364-21)
Dielectric Withstanding Voltage	No discharge, flashover or breakdown. Current leakage: 1 mA max.	500 VAC Min. at sea level for 1 minute.  Test between adjacent contacts of unmated connectors. (EIA-364-20)
Temperature rise	30°C Max. Change allowed	Mate connector: measure the temperature rise at rated current until temperature stable. The ambient condition is still air at 25°C (EIA-364-70,METHOD1,CONDITION1)
	MECHANICAL	
Durability	20 cycles.	The sample should be mounted in the tester and fully mated and unmated the number of cycles specified at the rate of 25.4 ± 3mm/min. (EIA-364-09)
Contact Retention Force	300gf Min.	Operation Speed:  25.4 ± 3 mm/minute.  Measure the contact retention force with Tensile strength tester.
FPC Insertion/Withdrawal Force	Refer to FPC Insertion/Withdrawal force	Insert the FPC and pull the FPC at the speed rate of 25.4 ± 3 mm/min.
Vibration	1 μs Max.	The electrical load condition shall be 100 mA maximum for all contacts. Subject to a simple harmonic motion having amplitude of 0.76mm (1.52mm maximum total excursion) in frequency between the limits of 10 and 55 Hz. The entire frequency range, from 10 to 55 Hz and return to 10 Hz, shall be traversed in approximately 1 minute. This motion shall be applied for 2 hours in each of three mutually perpendicular directions. (EIA-364-28 Condition I)
Shock (Mechanical)	1 μs Max.	Subject mated connectors to



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		50 G's (peak value) half-sine shock pulses of 11 milliseconds duration. Three shocks in each direction shall be applied along the three mutually perpendicular axes of the test specimen (18 shocks). The electrical load condition shall be
		100mA maximum for all contacts.
		(EIA-364-27, test condition A)
	ENVIRONMENTAI	_
Item	Requirement	Standard
Resistance to <b>Reflow</b> Soldering Heat	See Product Qualification and Test Sequence Group 10 (Lead Free)	Pre Heat : 150°C ~180°C, 60~120sec. Heat : 230°C Min., 40sec Min. Peak Temp. : 260°C Max, 10sec Max.
Thermal Shock	See Product Qualification and Test Sequence Group 4	Mate module and subject to follow condition for 5 cycles. 1 cycles: -55 +0/-3 °C, 30 minutes +85 +3/-0 °C, 30 minutes (EIA-364-32, test condition I)
Humidity	See Product Qualification and Test Sequence Group 4	Mated Connector 40°C, 90~95% RH, 96 hours. (EIA-364-31,Condition A, Method II)
Temperature life	See Product Qualification and Test Sequence Group 5	Subject mated connectors to temperature life at 85°C for 96 hours. (EIA-364-17, Test condition A)
Salt Spray (Only For Gold Plating)	See Product Qualification and Test Sequence Group 6	Subject mated/unmated connectors to 5% salt-solution concentration, 35°C (I) Gold flash for 8 hours (II) Gold plating 5 u" for 96 hours. (EIA-364-26)
Solder ability	Tin plating: Solder able area shall have minimum of 95% solder coverage. Gold plating: Solder able area shall have minimum of 75% solder coverage	And then into solder bath, Temperature at 245 ±5°C, for 4-5 sec. (EIA-364-52)
Hand Soldering	I	

Note. Flowing Mixed Gas shell be conduct by customer request.

Aces

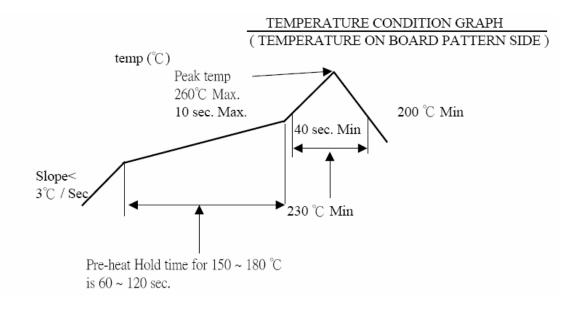
Aces P/N: 50687 series

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## **6 INFRARED REFLOW CONDITION**

6.1. Lead-free Process



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# 7 PRODUCT QUALIFICATION AND TEST SEQUENCE

					Те	st Gro	up								
Test or Examination		2	3	4	5	6	7	8	9	10	11				
	Test Sequence														
Examination of Product				1 . 7	1 . 6	1 \ 4				1	1				
Low Level Contact Resistance		1 \ 5	1 • 4	2 \ 10	2 . 9	2 ` 5				3					
Insulation Resistance				3、9	3、8										
Dielectric Withstanding Voltage				4、8	4 \ 7										
Temperature rise	1														
Durability		3													
Contact Retention Force									1						
Vibration			2												
Shock (Mechanical)			3												
Thermal Shock				5											
Humidity				6											
Temperature life					5										
Salt Spray(Only For Gold Plating)						3									
Solder ability							1								
FPC Insertion/Withdrawal Force		2,4						1							
Resistance to Soldering Heat										2					
Hand Soldering Temperature Resistance											2				
Sample Size	2	4	4	4	4	4	2	4	4	4	4				



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## 8 FPC INSERTION/WITHDRAWAL FORCE

NO. of	UNIT	Inserti	on Force	(MAX)	Withdi	rawal Ford	ce (Min)
Ckt.	ONII	1Cycle	6Cycles	20Cycles	1Cycle	6Cycles	20Cycles
4	kgf	2.45	1.90	1.90	0.24	0.23	0.23
5	kgf	2.60	2.05	2.05	0.25	0.24	0.24
6	kgf	2.75	2.20	2.20	0.26	0.25	0.25
7	kgf	2.90	3.35	3.35	0.27	0.26	0.26
8	kgf	3.05	2.50	2.50	0.28	0.27	0.27
9	kgf	3.20	2.65	2.65	0.29	0.28	0.28
10	kgf	3.35	2.80	2.80	0.34	0.33	0.33
11	kgf	3.50	2.95	2.95	0.35	0.34	0.34
12	kgf	3.65	3.10	3.10	0.36	0.35	0.35
13	kgf	3.80	3.25	3.25	0.37	0.36	0.36
14	kgf	3.95	3.40	3.40	0.38	0.37	0.37
15	kgf	4.10	3.55	3.55	0.39	0.38	0.38
16	kgf	4.25	3.70	3.70	0.40	0.39	0.39
17	kgf	4.40	3.85	3.85	0.41	0.40	0.40
18	kgf	4.55	4.00	4.00	0.42	0.41	0.41
19	kgf	4.70	4.15	4.15	0.43	0.42	0.42
20	kgf	4.85	4.30	4.30	0.44	0.43	0.43
21	kgf	5.00	4.45	4.45	0.45	0.44	0.44
22	kgf	5.15	4.60	4.60	0.46	0.45	0.45
23	kgf	5.30	4.75	4.75	0.47	0.46	0.46
24	kgf	5.45	4.90	4.90	0.48	0.47	0.47
25	kgf	5.60	5.05	5.05	0.49	0.48	0.48
26	kgf	5.75	5.20	5.20	0.50	0.49	0.49
27	kgf	5.90	5.35	5.35	0.51	0.50	0.50
28	kgf	6.05	5.50	5.50	0.52	0.51	0.51
29	kgf	6.20	5.65	5.65	0.53	0.52	0.52
30	kgf	6.35	5.80	5.80	0.54	0.53	0.53
31	kgf	6.50	5.95	5.95	0.55	0.54	0.54